

Fitting Instructions



ChipPanell 23F incorporates a resilient foam layer to reduce impact sound



ChipPanell 28/32F incorporates a resilient foam layer to reduce impact sound



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PREPARATION

Storage

Materials should be located into the environment in which they are to be fixed at least 24 hours prior to fixing. All components should be kept inside and in dry conditions at all times. Panels should be stacked flat on a level surface.

General - Subfloor

The base floor must be flat and dry with a minimum of 75% RH. Self Levelling screed may be required.

Reinforced concrete substrate

Apply a vapour-control layer may be required to protect against residual moisture vapour or a suitable sealer can be used.

Wooden substrates

To counter unevenness over 2-3mm of in the sub-floor/worn floor planks when directly installing the Chip Panel with a resilient layer, use a bulk leveller or suitable reinforced self-levelling screed unless the room has a high dynamic stress

Flanking strip

Minimum of 5mm flanking strip should be applied to the wall before installing Chip panel. The Chip Panel should pinch the flanking strip ensuring there is no gaps along the perimeter. If there is gaps, an acoustic mastic can be used to backfill.

Wet Conditions

Any components exposed to wet conditions such as rain, ingress of water or water leaks should be discarded. Precautions should be taken to avoid this where possible.

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Luxury Vinyl Tiles(LVT)

Before applying LVT a suitable self Levelling Screed should be applied and laid in accordance with manufacturer instructions

Engineered and solid Timber flooring

Engineered and solid Timber flooring can be bonded directly using a flexible adhesive recommended by the manufacturer. Where floor is being floated a suitable separating layer should be used to take out minor unevenness to avoid any hollows underneath the or rocking of the boards when installed.

Ceramic tiling / natural stone (up to 600mm side length)

Ceramic and Stone tiles can not be directly bonded to Chip Panel. Use a flexible tile adhesive system following the adhesive manufacturers instructions especially with regard to bed thickness. Along with a decoupling membrane. For larger format tiles please contact our technical team for advice.

Wet Areas

Chip Panel is not suitable for floors with high humidity and declined floors with drainage (e.g. wet rooms, commercial kitchens, swimming pools, Changing rooms etc). If full water resistance is needed please contact our technical team for advice.

Spanning applications

Not suitable for spanning joists or battens for raised floor applications. If you require the boards to span use the Screedboard Ultra or Chip Panel 37

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LAYING GUIDELINES

1. Cut off tongue at connection to wall figure 1
2. Start laying at the wall opposite the door to the left hand side
3. Panels can be installed without extra joints at doors. Figure 3
4. Prepare each board by placing a beads of SoundIs Chippanel Adhesive into groove joint.
5. Insert the tongue of the next board into the groove of the first board, ensuring they are tightly butted together, a small amount of adhesive should spill out of the joint.
6. Excess adhesive should be removed with a sharp floor scraper once dried.
7. Complete first run of boards then repeat steps 1-6 as per figure 2
8. Joints should be staggered by at least 200mm.
9. Avoid walking on the boards for 24 hours until the adhesive has completely dried.



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